

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2680464

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KUAN-WEI HUANG</td> <td>01/13/2014</td> </tr> <tr> <td>CHIA-YING LEE</td> <td>01/13/2014</td> </tr> <tr> <td>MING-CHUNG LIANG</td> <td>01/13/2014</td> </tr> </tbody> </table>		Name	Execution Date	KUAN-WEI HUANG	01/13/2014	CHIA-YING LEE	01/13/2014	MING-CHUNG LIANG	01/13/2014				
Name	Execution Date												
KUAN-WEI HUANG	01/13/2014												
CHIA-YING LEE	01/13/2014												
MING-CHUNG LIANG	01/13/2014												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>HSIN-CHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	HSIN-CHU SCIENCE PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.												
Street Address:	NO. 8, LI-HSIN RD. 6												
Internal Address:	HSIN-CHU SCIENCE PARK												
City:	HSIN-CHU												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14154439</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14154439								
Property Type	Number												
Application Number:	14154439												
CORRESPONDENCE DATA													
Fax Number: (216)502-0601 Phone: 216-502-0600 Email: docketing@eschweilerlaw.com <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i> Correspondent Name: ESCHWEILER & ASSOCIATES, LLC. Address Line 1: 629 EUCLID AVENUE, SUITE 1000 Address Line 2: NATIONAL CITY BANK BUILDING Address Line 4: CLEVELAND, OHIO 44114													
ATTORNEY DOCKET NUMBER:	TSMCP389US												
NAME OF SUBMITTER:	THOMAS G. ESCHWEILER												

Signature:	/Thomas G. Eschweiler/
Date:	01/14/2014
Total Attachments: 5 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif	

U.S. Patent Appln. No.

Docket No. TSMCP389US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Kuan-Wei Huang
5F, No. 135, Hongchang 6th St.
Taoyuan County
Taoyuan City 330
Taiwan (R.O.C.)

Assignor(s):

Chia-Ying Lee
No. 533, Xinzhuang Rd.
Xinzhuang Dist.
New Taipei City 242
Taiwan (R.O.C.)

Assignor(s):

Ming-Chung Liang
7F, No. 187, Ba-Der Road
Hsin-Chu City
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

“CUT FIRST SELF-ALIGNED LITHO-ETCH PATTERNING” for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration and Power of
Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

PATENT

REEL: 031960 FRAME: 0979

U.S. Patent Appln. No.

Docket No. TSMCP389US

Filing Date

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all

TSMC Docket No. TSMC2013-1704

U.S. Patent Appln. No.

Docket No. TSMCP389US

Filing Date

instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2014/1/13
Date

✓ 黃冠維. Kuan-Wei Huang.
Name 1st Inventor Kuan-Wei Huang

TSMC Docket No. TSMC2013-1704

Docket No. TSMCP389US

U.S. Patent Appln. No.

Filing Date

✓ 2014. 1. 13
Date

✓ Chia Ying Lee
Name 2nd Inventor/Chia-Ying Lee

PATENT

REEL: 031960 FRAME: 0982

U.S. Patent Appln. No.
Filing Date

TSMC Docket No. TSMC2013-1704

Docket No. TSMCP389US

✓ 2014/01/13
Date

✓ Ming-chung Liang
Name 3rd Inventor Ming-Chung Liang